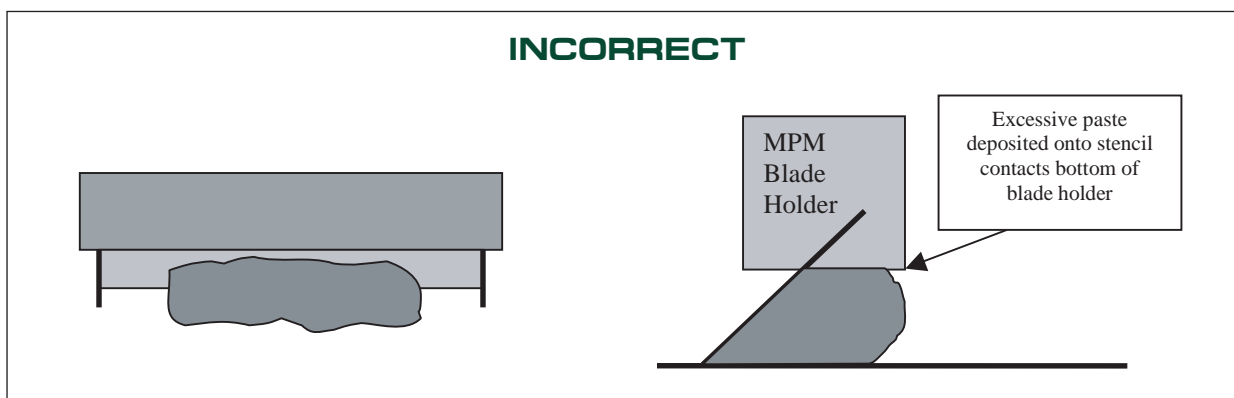
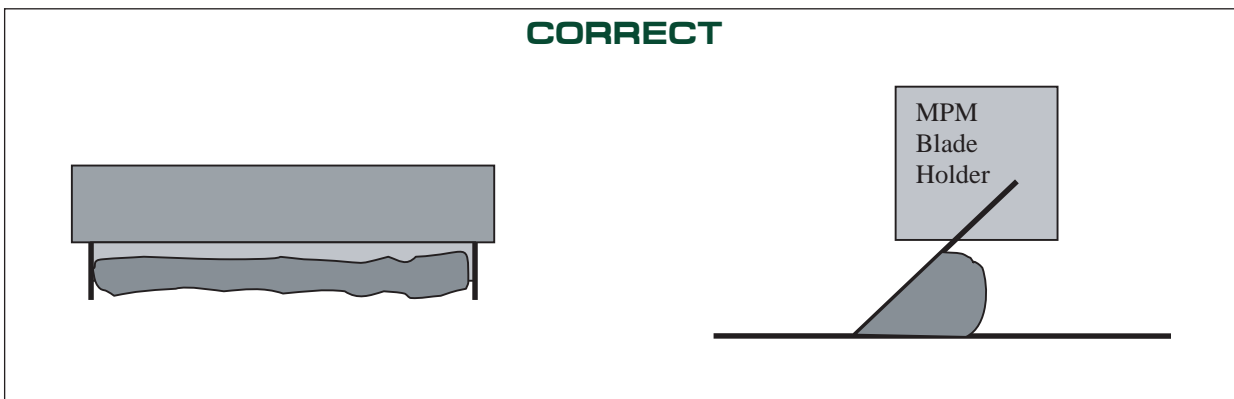


Solder Paste And Printer Recommendations For MPM UP3000 And AP25 Series Printers

SOLDER PASTE LOADING

- If using refrigerated storage, verify the solder paste has reached room temperature prior to use. The viscosity of cold solder paste can be excessively high causing numerous printing defects.
- Apply a uniform bead of solder paste (approximately 18 mm or 0.75 inches in diameter) along the entire length of the squeegee blade.
- Flatten with spatula to avoid contact with blade holder.
- If paste comes into contact with bottom of blade holder, remove and clean both the blade and holder.

Recommended Minimum Settings	
Print Speed:	50mm/second
Up Delay:	1.0 second
Lift Height:	25mm
Temperature:	23°C



This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

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S O L D E R

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